

Tool ID: 409  
Tool Location: 117

Equipment Information Sheet

# Heidelberg Mask Writer - DWL66FS

**Manager:**  
**Backup:**

**Garry Bordonaro**  
**John Treichler**

**607-254-4936**  
**607-254-4949**

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- System uses a class IIIb laser that is interlocked with chamber door to reduce the laser class to class I

**USAGE RESTRICTIONS**

**SCHEDULING/SIGN-UP RESTRICTIONS**

*Minimum Tool Time: 30 minutes*

- Maximum 4 hr block reservations anytime
- Maximum 12 hours reserved in advance

**MATERIALS COMPATIBILITY CATEGORY**

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

**High Vapor Pressure Metals and Compounds**are materials that have a vapor pressure above 1e-6 Torr at 400 C.

**Additional Material Restrictions and Exceptions**

- Masks Only - either 0.090" or 0.250" thick
- NO wafers, pieces or other substrates without Staff assistance

*Last Updated: 12/04/2020*